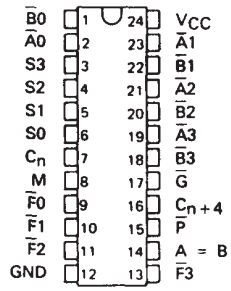
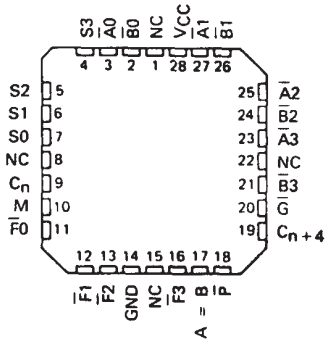
- Full Look-Ahead for High-Speed Operations on Long Words
- Input Clamping Diodes Minimize Transmission-Line Effects
- Darlington Outputs Reduce Turn-Off Time
- Arithmetic Operating Modes:
  - Addition
  - Subtraction
  - Shift Operand A One Position
  - Magnitude Comparison
  - Plus Twelve Other Arithmetic Operations
- Logic Function Modes:
  - Exclusive-OR
  - Comparator
  - AND, NAND, OR, NOR
  - Plus Ten Other Logic Operations

SN54LS181, SN54S181 . . . J OR W PACKAGE
SN74LS181, SN74S181 . . . DW OR N PACKAGE
(TOP VIEW)



SN54LS181, SN54S181 . . . FK PACKAGE
(TOP VIEW)



NC - No internal connection

TYPICAL ADDITION TIMES

NUMBER OF BITS	ADDITION TIMES USING 'LS181 AND 'S182	ADDITION TIMES USING 'S181 AND 'S182	PACKAGE COUNT ARITHMETIC/ LOGIC UNITS	PACKAGE COUNT LOOK-AHEAD CARRY GENERATORS	CARRY METHOD BETWEEN ALUs
1 to 4	24 ns	11 ns	1		NONE
5 to 8	40 ns	18 ns	2		RIPPLE
9 to 16	44 ns	19 ns	3 or 4	1	FULL LOOK-AHEAD
17 to 64	68 ns	28 ns	5 to 16	2 to 5	FULL LOOK-AHEAD

description

The 'LS181 and 'S181 are arithmetic logic units (ALU)/function generators that have a complexity of 75 equivalent gates on a monolithic chip. These circuits perform 16 binary arithmetic operations on two 4-bit words as shown in Tables 1 and 2. These operations are selected by the four function-select lines (S0, S1, S2, S3) and include addition, subtraction, decrement, and straight transfer. When performing arithmetic manipulations, the internal carries must be enabled by applying a low-level voltage to the mode control input (M). A full carry look-ahead scheme is made available in these devices for fast, simultaneous carry generation by means of two cascade-outputs (pins 15 and 17) for the four bits in the package. When used in conjunction with the SN54S182 or SN74S182 full carry look-ahead circuits, high-speed arithmetic operations can be performed. The typical addition times shown above illustrate the little additional time required for addition of longer words when full carry look-ahead is employed. The method of cascading 'S182 circuits with these ALUs to provide multi-level full carry look-ahead is illustrated under typical applications data for the 'S182.

If high speed is not of importance, a ripple-carry input (C_n) and a ripple-carry output (C_{n+4}) are available. However, the ripple-carry delay has also been minimized so that arithmetic manipulations for small word lengths can be performed without external circuitry.

description (continued)

The 'LS181 and 'S181 will accommodate active-high data if the pin designations are interpreted as follows:

PIN NUMBER	2	1	23	22	21	20	19	18	9	10	11	13	7	16	15	17
Active-low data (Table 1)	$\overline{A}_0$	$\overline{B}_0$	$\overline{A}_1$	$\overline{B}_1$	$\overline{A}_2$	$\overline{B}_2$	$\overline{A}_3$	$\overline{B}_3$	$\overline{F}_0$	$\overline{F}_1$	$\overline{F}_2$	$\overline{F}_3$	C_n	C_{n+4}	$\overline{P}$	$\overline{G}$
Active-high data (Table 2)	A_0	B_0	A_1	B_1	A_2	B_2	A_3	B_3	F_0	F_1	F_2	F_3	$\overline{C}_n$	$\overline{C}_{n+4}$	X	Y

Subtraction is accomplished by 1's complement addition where the 1's complement of the subtrahend is generated internally. The resultant output is A–B–1, which requires an end-around or forced carry to provide A–B.

The 'LS181 or 'S181 can also be utilized as a comparator. The A = B output is internally decoded from the function outputs (F0, F1, F2, F3) so that when two words of equal magnitude are applied at the A and B inputs, it will assume a high level to indicate equality (A = B). The ALU must be in the subtract mode with C_n = H when performing this comparison. The A = B output is open-collector so that it can be wire-AND connected to give a comparison for more than four bits. The carry output (C_{n+4}) can also be used to supply relative magnitude information. Again, the ALU must be placed in the subtract mode by placing the function select inputs S3, S2, S1, S0 at L, H, H, L, respectively.

INPUT C_n	OUTPUT C_{n+4}	ACTIVE-LOW DATA (FIGURE 1)	ACTIVE-HIGH DATA (FIGURE 2)
H	H	A ≥ B	A ≤ B
H	L	A < B	A > B
L	H	A > B	A < B
L	L	A ≤ B	A ≥ B

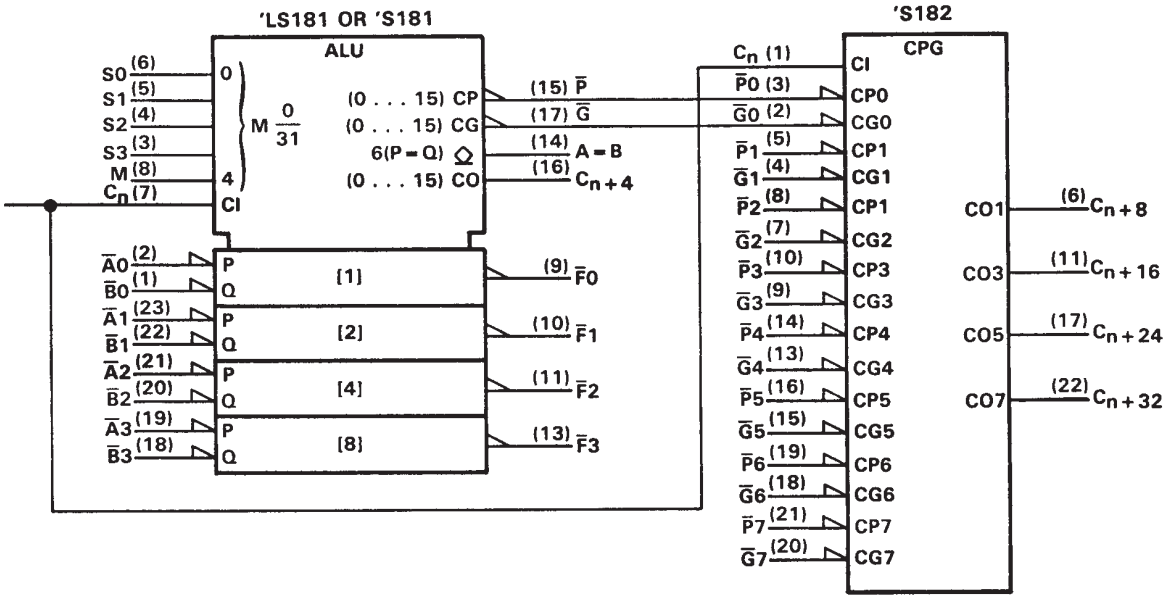
These circuits have been designed to not only incorporate all of the designer's requirements for arithmetic operations, but also to provide 16 possible functions of two Boolean variables without the use of external circuitry. These logic functions are selected by use of the four function-select inputs (S0, S1, S2, S3) with the mode-control input (M) at a high level to disable the internal carry. The 16 logic functions are detailed in Tables 1 and 2 and include exclusive-OR, NAND, AND, NOR, and OR functions.

Series 54, 54LS, and 54S devices are characterized for operation over the full military temperature range of −55°C to 125°C; Series 74LS and 74S devices are characterized for operation from 0°C to 70°C.

signal designations

In both Figures 1 and 2, the polarity indicators (◺) indicate that the associated input or output is active-low with respect to the function shown inside the symbol, and the symbols are the same in both figures. The signal designations in Figure 1 agree with the indicated internal functions based on active-low data, and are for use with the logic functions and arithmetic operations shown in Table 1. The signal designations have been changed in Figure 2 to accommodate the logic functions and arithmetic operations for the active-high data given in Table 2. The 'LS181 and 'S181, together with the 'S182, can be used with the signal designation of either Figure 1 or Figure 2.

logic symbols† and signal designations (active-low data)



†These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.
Pin numbers shown are for dual-in-line and "small outline" packages.

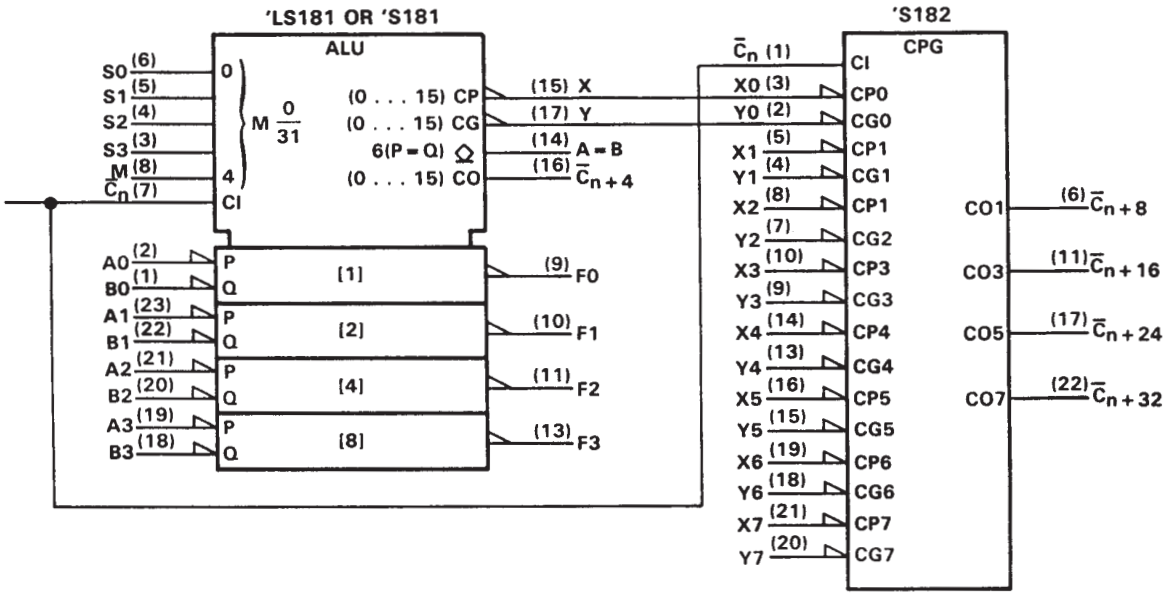
FIGURE 1 (USE WITH TABLE 1)

TABLE 1

SELECTION				ACTIVE-LOW DATA		
				M = H	M = L; ARITHMETIC OPERATIONS	
S3	S2	S1	S0	LOGIC FUNCTIONS	Cn = L (no carry)	Cn = H (with carry)
L	L	L	L	F = $\overline{A}$	F = A MINUS 1	F = A
L	L	L	H	F = $\overline{AB}$	F = AB MINUS 1	F = AB
L	L	H	L	F = $\overline{A}$ + B	F = A$\overline{B}$ MINUS 1	F = A$\overline{B}$
L	L	H	H	F = 1	F = MINUS 1 (2's COMP)	F = ZERO
L	H	L	L	F = $\overline{A + B}$	F = A PLUS (A + $\overline{B}$)	F = A PLUS (A + $\overline{B}$) PLUS 1
L	H	L	H	F = $\overline{B}$	F = AB PLUS (A + $\overline{B}$)	F = AB PLUS (A + $\overline{B}$) PLUS 1
L	H	H	L	F = $\overline{A \oplus B}$	F = A MINUS B MINUS 1	F = A MINUS B
L	H	H	H	F = A + $\overline{B}$	F = A + $\overline{B}$	F = (A + $\overline{B}$) PLUS 1
H	L	L	L	F = $\overline{A}$B	F = A PLUS (A + B)	F = A PLUS (A + B) PLUS 1
H	L	L	H	F = A $\oplus$ B	F = A PLUS B	F = A PLUS B PLUS 1
H	L	H	L	F = B	F = A$\overline{B}$ PLUS (A + B)	F = A$\overline{B}$ PLUS (A + B) PLUS 1
H	L	H	H	F = A + B	F = (A + B)	F = (A + B) PLUS 1
H	H	L	L	F = 0	F = A PLUS A‡	F = A PLUS A PLUS 1
H	H	L	H	F = A$\overline{B}$	F = AB PLUS A	F = AB PLUS A PLUS 1
H	H	H	L	F = AB	F = A$\overline{B}$ PLUS A	F = A$\overline{B}$ PLUS A PLUS 1
H	H	H	H	F = A	F = A	F = A PLUS 1

‡Each bit is shifted to the next more significant position.

logic symbols† and signal designations (active-high data)



†These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.
Pin numbers shown are for dual-in-line and "small outline" packages.

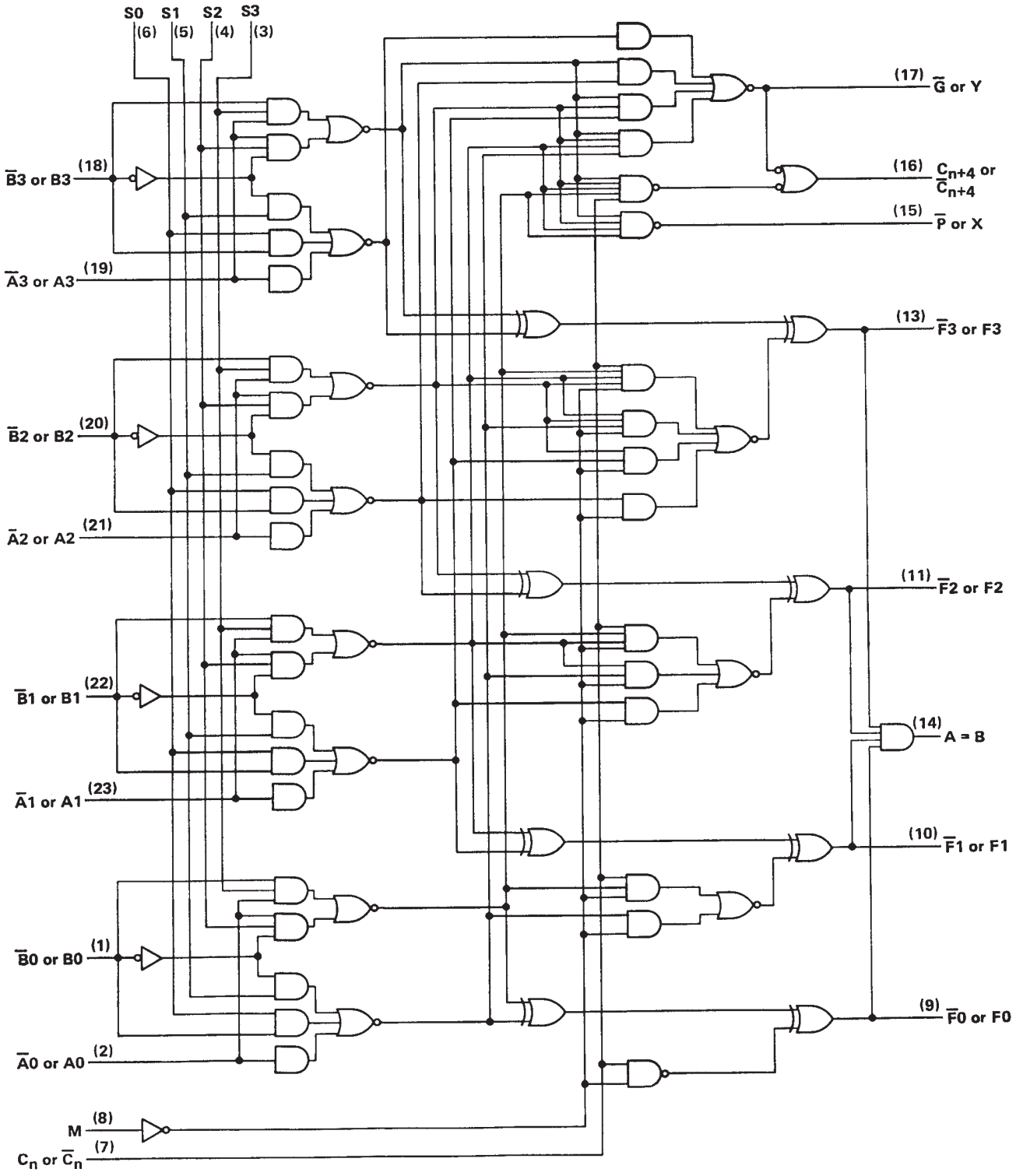
FIGURE 2 (USE WITH TABLE 2)

TABLE 2

SELECTION				ACTIVE-HIGH DATA		
				M = H	M = L; ARITHMETIC OPERATIONS	
S3	S2	S1	S0	LOGIC FUNCTIONS	$\overline{C_n}$ = H (no carry)	$\overline{C_n}$ = L (with carry)
L	L	L	L	$F = \overline{A}$	F = A	F = A PLUS 1
L	L	L	H	$F = \overline{A + B}$	F = A + B	F = (A + B) PLUS 1
L	L	H	L	$F = \overline{A}B$	$F = A + \overline{B}$	$F = (A + \overline{B})$ PLUS 1
L	L	H	H	F = 0	F = MINUS 1 (2's COMPL)	F = ZERO
L	H	L	L	$F = \overline{AB}$	$F = A$ PLUS $A\overline{B}$	$F = A$ PLUS $A\overline{B}$ PLUS 1
L	H	L	H	$F = \overline{B}$	$F = (A + B)$ PLUS $A\overline{B}$	$F = (A + B)$ PLUS $A\overline{B}$ PLUS 1
L	H	H	L	$F = A \oplus B$	F = A MINUS B MINUS 1	F = A MINUS B
L	H	H	H	$F = A\overline{B}$	$F = A\overline{B}$ MINUS 1	$F = A\overline{B}$
H	L	L	L	$F = \overline{A} + B$	F = A PLUS AB	F = A PLUS AB PLUS 1
H	L	L	H	$F = \overline{A \oplus B}$	F = A PLUS B	F = A PLUS B PLUS 1
H	L	H	L	F = B	$F = (A + \overline{B})$ PLUS AB	$F = (A + \overline{B})$ PLUS AB PLUS 1
H	L	H	H	F = AB	F = AB MINUS 1	F = AB
H	H	L	L	F = 1	F = A PLUS A†	F = A PLUS A PLUS 1
H	H	L	H	$F = A + \overline{B}$	F = (A + B) PLUS A	F = (A + B) PLUS A PLUS 1
H	H	H	L	F = A + B	$F = (A + \overline{B})$ PLUS A	$F = (A + \overline{B})$ PLUS A PLUS 1
H	H	H	H	F = A	F = A MINUS 1	F = A

† Each bit is shifted to the next more significant position.

logic diagram (positive logic)



Pin numbers shown are for DW, J, N, and W packages.

absolute maximum ratings over recommended operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 5.5 V
Interemitter voltage (see Note 2) . . . . . 5.5 V
Operating free-air temperature range: SN54LS181 . . . . . −55°C to 125°C
SN74LS181 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTES: 1. Voltage values, except interemitter voltage, are with respect to network ground terminal.
2. This is the voltage between two emitters of a multiple-emitter transistor. For this circuit, this rating applies to each $\overline{A}$ input in conjunction with inputs S2 or S3, and to each $\overline{B}$ input in conjunction with inputs S0 or S3.

recommended operating conditions

	SN54LS181			SN74LS181			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH} (All outputs except A = B)			−400			−400	μA
Low-level output current, I_{OL}			4			8	mA
Operating free-air temperature, T_A	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†		SN54LS181			SN74LS181			UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage				2			2			V
V_{IL}	Low-level input voltage						0.7			0.8	V
V_{IK}	Input clamp voltage		V_{CC} = MIN, I_I = −18 mA				−1.5			−1.5	V
V_{OH}	High-level output voltage, any output except A = B		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = V_{IL} max, I_{OH} = −400 μA		2.5	3.4		2.7	3.4		V
I_{OH}	High-level output current, A = B output only		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = V_{IL} max, V_{OH} = 5.5 V				100			100	μA
V_{OL}	Low-level output voltage	All outputs	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = V_{IL} max	I_{OL} = 4 mA		0.25	0.4		0.25	0.4	V
				I_{OL} = 8 mA					0.35	0.5	
		Output $\overline{G}$		I_{OL} = 16 mA		0.47	0.7		0.47	0.7	
		Output $\overline{P}$		I_{OL} = 8 mA		0.35	0.6		0.35	0.5	
I_I	Input current at max. input voltage	Mode input	V_{CC} = MAX, V_I = 5.5 V				0.1			0.1	mA
		Any $\overline{A}$ or $\overline{B}$ input					0.3			0.3	
		Any S input					0.4			0.4	
		Carry input					0.5			0.5	
I_{IH}	High-level input current	Mode input	V_{CC} = MAX, V_I = 2.7 V				20			20	μA
		Any $\overline{A}$ or $\overline{B}$ input					60			60	
		Any S input					80			80	
		Carry input					100			100	
I_{IL}	Low-level input current	Mode input	V_{CC} = MAX, V_I = 0.4 V				−0.4			−0.4	mA
		Any $\overline{A}$ or $\overline{B}$ input					−1.2			−1.2	
		Any S input					−1.6			−1.6	
		Carry input					−2			−2	
I_{OS}	Short-circuit output current, any output except A = B§		V_{CC} = MAX		−6		−40	−5		−42	mA
I_{CC}	Supply current		V_{CC} = MAX, See Note 3	Condition A		20	32		20	34	mA
				Condition B		21	35		21	37	

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
§Not more than one output should be shorted at a time.
NOTE 3: With outputs open, I_{CC} is measured for the following conditions:
A. S0 through S3, M, and $\overline{A}$ inputs are at 4.5 V, all other inputs are grounded.
B. S0 through S3 and M are at 4.5 V, all other inputs are grounded.

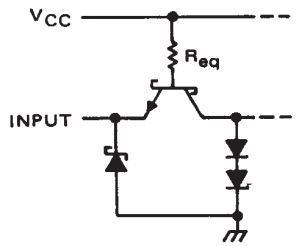
switching characteristics, V_{CC} = 5 V, T_A = 25°C, (C_L = 15 pF, R_L = 2 kΩ, see note 4)

PARAMETER†	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	C_n	C_{n+4}			18	27	ns
t_{PHL}					13	20	
t_{PLH}	Any $\overline{A}$ or $\overline{B}$	C_{n+4}	M = 0 V, S0 = S3 = 4.5 V, S1 = S2 = 0 V ($\overline{SUM}$ mode)		25	38	ns
t_{PHL}					25	38	
t_{PLH}	Any $\overline{A}$ or $\overline{B}$	C_{n+4}	M = 0 V, S0 = S3 = 0 V S1 = S2 = 4.5 V ($\overline{DIFF}$ mode)		27	41	ns
t_{PHL}					27	41	
t_{PLH}	C_n	Any $\overline{F}$	M = 0 V ($\overline{SUM}$ or $\overline{DIFF}$ mode)		17	26	ns
t_{PHL}					13	20	
t_{PLH}	Any $\overline{A}$ or $\overline{B}$	$\overline{G}$	M = 0 V, S0 = S3 = 4.5 V, S1 = S2 = 0 V ($\overline{SUM}$ mode)		19	29	ns
t_{PHL}					15	23	
t_{PLH}	Any $\overline{A}$ or $\overline{B}$	$\overline{G}$	M = 0 V, S0 = S3 = 0 V, S1 = S2 = 4.5 V ($\overline{DIFF}$ mode)		21	32	ns
t_{PHL}					21	32	
t_{PLH}	Any $\overline{A}$ or $\overline{B}$	$\overline{P}$	M = 0 V, S0 = S3 = 4.5 V, S1 = S2 = 0 V, ($\overline{SUM}$ mode)		20	30	ns
t_{PHL}					20	30	
t_{PLH}	Any $\overline{A}$ or $\overline{B}$	$\overline{P}$	M = 0 V, S0 = S3 = 0 V, S1 = S2 = 4.5 V ($\overline{DIFF}$ mode)		20	30	ns
t_{PHL}					22	33	
t_{PLH}	$\overline{A}_i$ or $\overline{B}_i$	$\overline{F}_i$	M = 0 V, S0 = S3 = 4.5 V, S1 = S2 = 0 V ($\overline{SUM}$ mode)		21	32	ns
t_{PHL}					13	20	
t_{PLH}	$\overline{A}_i$ or $\overline{B}_i$	$\overline{F}_i$	M = 0 V, S0 = S3 = 0 V, S1 = S2 = 4.5 V ($\overline{DIFF}$ mode)		21	32	ns
t_{PHL}					21	32	
t_{PLH}	$\overline{A}_i$ or $\overline{B}_i$	$\overline{F}_i$	M = 4.5 V (logic mode)		22	33	ns
t_{PHL}					26	38	
t_{PLH}	Any $\overline{A}$ or $\overline{B}$	A = B	M = 0 V, S0 = S3 = 0 V, S1 = S2 = 4.5 V ($\overline{DIFF}$ mode)		33	50	ns
t_{PHL}					41	62	

†t_{PLH} = propagation delay time, low-to-high-level output
t_{PHL} = propagation delay time, high-to-low-level output
NOTE 4: Load circuits and voltage wveforms are shown in Section 1. Refer to Parameter Measurement Information page for test conditions.

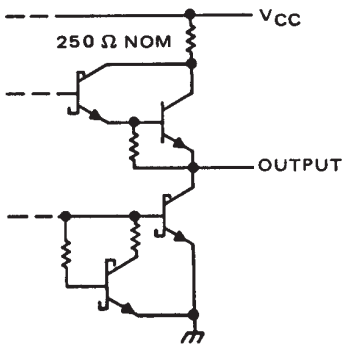
schematics of inputs and outputs

EQUIVALENT OF EACH INPUT

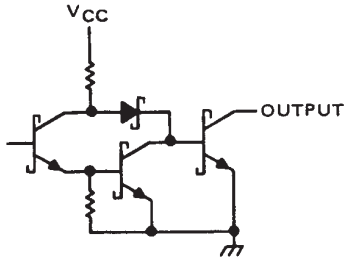


Mode control: R_{eq} = 17 kΩ NOM
Any $\overline{A}$ or $\overline{B}$: R_{eq} = 5.67 kΩ NOM
Any S: R_{eq} = 4.25 kΩ NOM
C_n: R_{eq} = 2.86 kΩ NOM

TYPICAL OF ALL OUTPUTS EXCEPT A = B



A = B OUTPUT



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 5.5 V
Interemitter voltage (see Note 2) . . . . . 5.5 V
Operating free-air temperature: SN54S181 . . . . . −55°C to 125°C
SN74S181 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTES: 1. Voltage values, except interemitter voltage, are with respect to network ground terminal.
2. This is the voltage between two emitters of a multiple-emitter transistor. For this circuit, this rating applies to each $\overline{A}$ input in conjunction with inputs S2 or S3, and to each $\overline{B}$ input in conjunction with inputs S0 or S3.

recommended operating conditions

	SN54S181			SN74S181			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH} (All outputs except A = B)			−1			−1	mA
Low-level output current, I_{OL}			20			20	mA
Operating free-air temperature, T_A	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†			SN54S181			SN74S181			UNIT
						MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage					2			2			V
V_{IL}	Low-level input voltage							0.8			0.8	V
V_{IK}	Input clamp voltage		V_{CC} = MIN,	I_I = −18 mA				−1.2			−1.2	V
V_{OH}	High-level output voltage, any output except A = B		V_{CC} = MIN, V_{IL} = 0.8 V,	V_{IH} = 2 V, I_{OH} = −1 mA		2.5	3.4		2.7	3.4		V
I_{OH}	High-level output current, A = B output only		V_{CC} = MIN, V_{IL} = 0.8 V,	V_{IH} = 2 V, V_{OH} = 5.5 V				250			250	μA
V_{OL}	Low-level output voltage		V_{CC} = MIN, V_{IL} = 0.8 V,	V_{IH} = 2 V, I_{OL} = 20 mA				0.5			0.5	V
I_I	Input current at maximum input voltage		V_{CC} = MAX,	V_I = 5.5 V				1			1	mA
I_{IH}	High-level input current	Mode input	V_{CC} = MAX,	V_I = 2.5 V				50			50	μA
		Any $\overline{A}$ or $\overline{B}$ input						150			150	
		Any S input						200			200	
		Carry input						250			250	
I_{IL}	Low-level input current	Mode input	V_{CC} = MAX,	V_I = 0.5 V				−2			−2	mA
		Any $\overline{A}$ or $\overline{B}$ input						−6			−6	
		Any S input						−8			−8	
		Carry input						−10			−10	
I_{OS}	Short-circuit output current, any output except A = B§		V_{CC} = MAX			−40		−100	−40		−100	mA
I_{CC}	Supply current		V_{CC} = MAX, See Note 3	T_A = 125°C,	W package only			195				mA
			V_{CC} = MAX,	See Note 3	All packages		120	220		120	220	

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
§Not more than one output should be shorted at a time.
NOTE 3: I_{CC} is measured for the following conditions (the typical and maximum values apply to both):
A. S0 through S3, M, and $\overline{A}$ inputs are at 4.5 V, all other inputs are grounded, and all outputs are open.
B. S0 through S3 and M are at 4.5 V, all other inputs grounded, and all outputs are open.

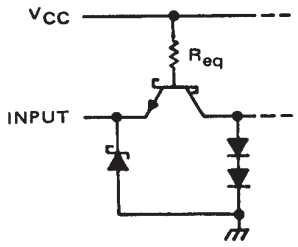
switching characteristics, V_{CC} = 5 V, T_A = 25°C (C_L = 15 pF, R_L = 280 Ω, see note 4)

PARAMETER†	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	C_n	C_{n+4}			7	10.5	ns
t_{PHL}					7	10.5	
t_{PLH}	Any $\overline{A}$ or $\overline{B}$	C_{n+4}	M = 0 V, S0 = S3 = 4.5 V, S1 = S2 = 0 V ($\overline{SUM}$ mode)		12.5	18.5	ns
t_{PHL}					12.5	18.5	
t_{PLH}	Any $\overline{A}$ or $\overline{B}$	C_{n+4}	M = 0 V, S0 = S3 = 0 V, S1 = S2 = 4.5 V ($\overline{DIFF}$ mode)		15.5	23	ns
t_{PHL}					15.5	23	
t_{PLH}	C_n	Any $\overline{F}$	M = 0 V ($\overline{SUM}$ or $\overline{DIFF}$ mode)		7	12	ns
t_{PHL}					7	12	
t_{PLH}	Any $\overline{A}$ or $\overline{B}$	$\overline{G}$	M = 0 V, S0 = S3 = 4.5 V, S1 = S2 = 0 V ($\overline{SUM}$ mode)		8	12	ns
t_{PHL}					7.5	12	
t_{PLH}	Any $\overline{A}$ or $\overline{B}$	$\overline{G}$	M = 0 V, S0 = S3 = 0 V, S1 = S2 = 4.5 V ($\overline{DIFF}$ mode)		10.5	15	ns
t_{PHL}					10.5	15	
t_{PLH}	Any $\overline{A}$ or $\overline{B}$	$\overline{P}$	M = 0 V, S0 = S3 = 4.5 V, S1 = S2 = 0 V ($\overline{SUM}$ mode)		7.5	12	ns
t_{PHL}					7.5	12	
t_{PLH}	Any $\overline{A}$ or $\overline{B}$	$\overline{P}$	M = 0 V, S0 = S3 = 0 V, S1 = S2 = 4.5 V ($\overline{DIFF}$ mode)		10.5	15	ns
t_{PHL}					10.5	15	
t_{PLH}	$\overline{A}_i$ or $\overline{B}_i$	$\overline{F}_i$	M = 0 V, S0 = S3 = 4.5 V, S1 = S2 = 0 V ($\overline{SUM}$ mode)		11	16.5	ns
t_{PHL}					11	16.5	
t_{PLH}	$\overline{A}_i$ or $\overline{B}_i$	$\overline{F}_i$	M = 0 V, S0 = S3 = 0 V, S1 = S2 = 4.5 V ($\overline{DIFF}$ mode)		14	20	ns
t_{PHL}					14	22	
t_{PLH}	$\overline{A}_i$ or $\overline{B}_i$	$\overline{F}_i$	M = 4.5 V (logic mode)		14	20	ns
t_{PHL}					14	22	
t_{PLH}	Any $\overline{A}$ or $\overline{B}$	A = B	M = 0 V, S0 = S3 = 0 V, S1 = S2 = 4.5 V ($\overline{DIFF}$ mode)		15	23	ns
t_{PHL}					20	30	

†t_{PLH} ≡ propagation delay time, low-to-high-level output
t_{PHL} ≡ propagation delay time, high-to-low-level output
NOTE 4: Load circuits and voltage wveforms are shown in Section 1. Refer to Parameter Measurement Information page for test conditions.

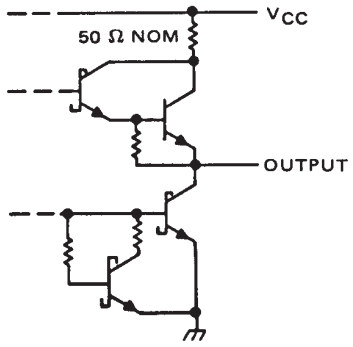
schematics of inputs and outputs

EQUIVALENT OF EACH INPUT

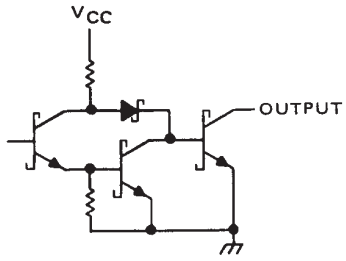


Mode control: R_{eq} = 2.8 kΩ NOM
Any $\overline{A}$ or $\overline{B}$: R_{eq} = 940 Ω NOM
Any S: R_{eq} = 700 Ω NOM
C_n: R_{eq} = 560 Ω NOM

TYPICAL OF ALL OUTPUTS EXCEPT A = B



A = B OUTPUT



PARAMETER MEASUREMENT INFORMATION

$\overline{SUM}$ MODE TEST TABLE

FUNCTION INPUTS: S0 = S3 = 4.5 V, S1 = S2 = M = 0 V

PARAMETER	INPUT UNDER TEST	OTHER INPUT SAME BIT		OTHER DATA INPUTS		OUTPUT UNDER TEST	OUTPUT WAVEFORM (See Note 4)
		APPLY 4.5 V	APPLY GND	APPLY 4.5 V	APPLY GND		
t_{PLH} / t_{PHL}	$\overline{A}_i$	$\overline{B}_i$	None	Remaining $\overline{A}$ and $\overline{B}$	C_n	$\overline{F}_i$	In-Phase
t_{PLH} / t_{PHL}	$\overline{B}_i$	$\overline{A}_i$	None	Remaining $\overline{A}$ and $\overline{B}$	C_n	$\overline{F}_i$	In-Phase
t_{PLH} / t_{PHL}	$\overline{A}_i$	$\overline{B}_i$	None	None	Remaining $\overline{A}$ and $\overline{B}$, C_n	$\overline{P}$	In-Phase
t_{PLH} / t_{PHL}	$\overline{B}_i$	$\overline{A}_i$	None	None	Remaining $\overline{A}$ and $\overline{B}$, C_n	$\overline{P}$	In-Phase
t_{PLH} / t_{PHL}	$\overline{A}_i$	None	$\overline{B}_i$	Remaining $\overline{B}$	Remaining $\overline{A}$, C_n	$\overline{G}$	In-Phase
t_{PLH} / t_{PHL}	$\overline{B}_i$	None	$\overline{A}_i$	Remaining $\overline{B}$	Remaining $\overline{A}$, C_n	$\overline{G}$	In-Phase
t_{PLH} / t_{PHL}	C_n	None	None	All $\overline{A}$	All $\overline{B}$	Any $\overline{F}$ or C_{n+4}	In-Phase
t_{PLH} / t_{PHL}	$\overline{A}_i$	None	$\overline{B}_i$	Remaining $\overline{B}$	Remaining $\overline{A}$, C_n	C_{n+4}	Out-of-Phase
t_{PLH} / t_{PHL}	$\overline{B}_i$	None	$\overline{A}_i$	Remaining $\overline{B}$	Remaining $\overline{A}$, C_n	C_{n+4}	Out-of-Phase

$\overline{DIFF}$ MODE TEST TABLE

FUNCTION INPUTS: S1 = S2 = 4.5 V, S0 = S3 = M = 0 V

PARAMETER	INPUT UNDER TEST	OTHER INPUT SAME BIT		OTHER DATA INPUTS		OUTPUT UNDER TEST	OUTPUT WAVEFORM (See Note 4)
		APPLY 4.5 V	APPLY GND	APPLY 4.5 V	APPLY GND		
t_{PLH} / t_{PHL}	$\overline{A}_i$	None	$\overline{B}_i$	Remaining $\overline{A}$	Remaining $\overline{B}$, C_n	$\overline{F}_i$	In-Phase
t_{PLH} / t_{PHL}	$\overline{B}_i$	$\overline{A}_i$	None	Remaining $\overline{A}$	Remaining $\overline{B}$, C_n	$\overline{F}_i$	Out-of-Phase
t_{PLH} / t_{PHL}	$\overline{A}_i$	None	$\overline{B}_i$	None	Remaining $\overline{A}$ and $\overline{B}$, C_n	$\overline{P}$	In-Phase
t_{PLH} / t_{PHL}	$\overline{B}_i$	$\overline{A}_i$	None	None	Remaining $\overline{A}$ and $\overline{B}$, C_n	$\overline{P}$	Out-of-Phase
t_{PLH} / t_{PHL}	$\overline{A}_i$	$\overline{B}_i$	None	None	Remaining $\overline{A}$ and $\overline{B}$, C_n	$\overline{G}$	In-Phase
t_{PLH} / t_{PHL}	$\overline{B}_i$	None	$\overline{A}_i$	None	Remaining $\overline{A}$ and $\overline{B}$, C_n	$\overline{G}$	Out-of-Phase
t_{PLH} / t_{PHL}	$\overline{A}_i$	None	$\overline{B}_i$	Remaining $\overline{A}$	Remaining $\overline{B}$, C_n	A = B	In-Phase
t_{PLH} / t_{PHL}	$\overline{B}_i$	$\overline{A}_i$	None	Remaining $\overline{A}$	Remaining $\overline{B}$, C_n	A = B	Out-of Phase
t_{PLH} / t_{PHL}	C_n	None	None	All $\overline{A}$ and $\overline{B}$	None	C_{n+4} or any $\overline{F}$	In-Phase
t_{PLH} / t_{PHL}	$\overline{A}_i$	$\overline{B}_i$	None	None	Remaining $\overline{A}$, $\overline{B}$, C_n	C_{n+4}	Out-of-Phase
t_{PLH} / t_{PHL}	$\overline{B}_i$	None	$\overline{A}_i$	None	Remaining $\overline{A}$, $\overline{B}$, C_n	C_{n+4}	In -Phase

LOGIC MODE TEST TABLE

FUNCTION INPUTS: S1 = S2 = M = 4.5 V, S0 = S3 = 0 V

PARAMETER	INPUT UNDER TEST	OTHER INPUT SAME BIT		OTHER DATA INPUTS		OUTPUT UNDER TEST	OUTPUT WAVEFORM (See Note 4)
		APPLY 4.5 V	APPLY GND	APPLY 4.5 V	APPLY GND		
t_{PLH} / t_{PHL}	$\overline{A}_i$	$\overline{B}_i$	None	None	Remaining $\overline{A}$ and $\overline{B}$, C_n	$\overline{F}_i$	Out-of-Phase
t_{PLH} / t_{PHL}	$\overline{B}_i$	$\overline{A}_i$	None	None	Remaining $\overline{A}$ and $\overline{B}$, C_n	$\overline{F}_i$	Out-of-Phase

NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/07801BJA	ACTIVE	CDIP	J	24	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 07801BJA	Samples
M38510/07801BJA	ACTIVE	CDIP	J	24	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	JM38510/ 07801BJA	Samples
SN54LS181J	ACTIVE	CDIP	J	24	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SN54LS181J	Samples
SN54S181J	ACTIVE	CDIP	J	24	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SN54S181J	Samples
SN74LS181N3	OBSOLETE	PDIP	N	24		TBD	Call TI	Call TI	0 to 70		
SN74S181J	OBSOLETE	CDIP	J	24		TBD	Call TI	Call TI	0 to 70		
SN74S181N	OBSOLETE	PDIP	N	24		TBD	Call TI	Call TI	0 to 70		
SN74S181N3	OBSOLETE	PDIP	N	24		TBD	Call TI	Call TI	0 to 70		
SNJ54LS181J	ACTIVE	CDIP	J	24	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SNJ54LS181J	Samples
SNJ54S181J	ACTIVE	CDIP	J	24	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SNJ54S181J	Samples
SNJ54S181W	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S181W	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF SN54LS181, SN54S181, SN74LS181, SN74S181 :

- Catalog: SN74LS181, SN74S181
- Military: SN54LS181, SN54S181

NOTE: Qualified Version Definitions:

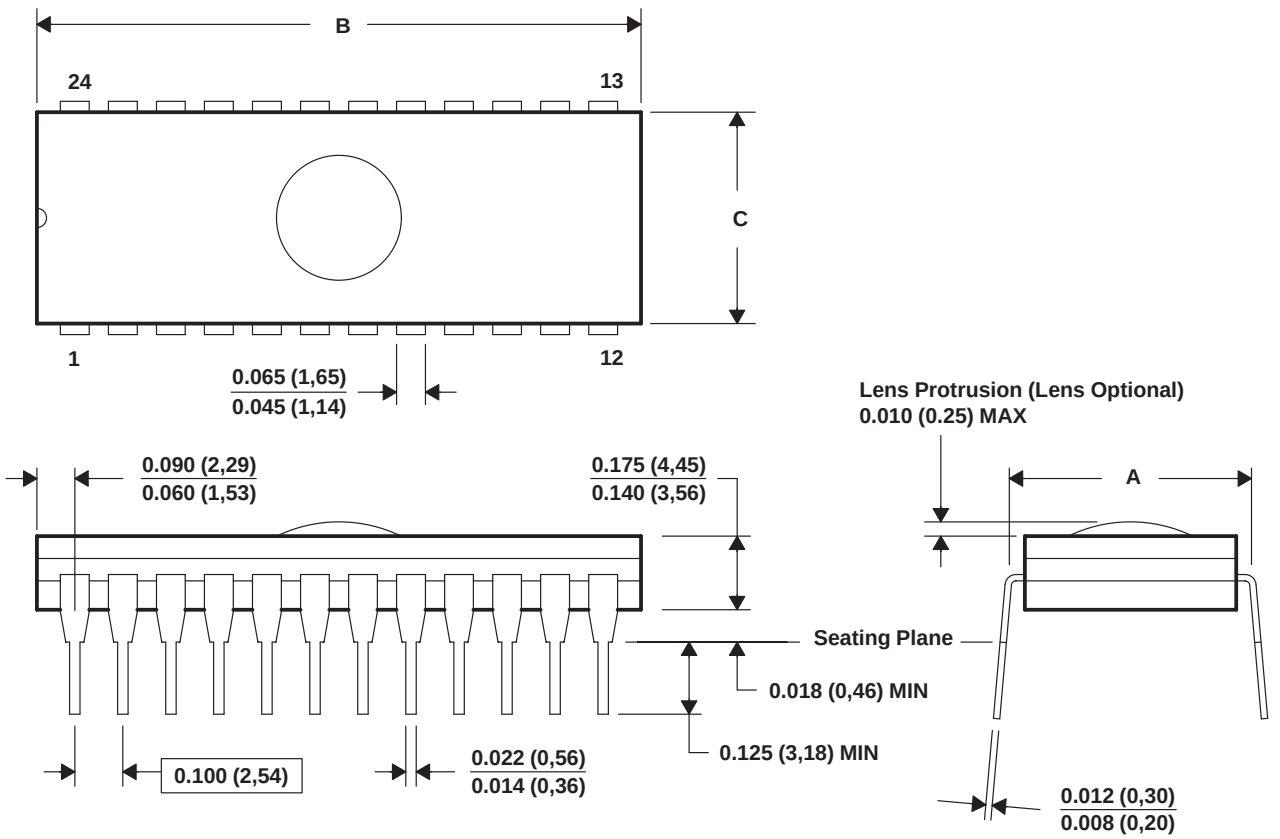
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

MCDI004A – JANUARY 1995 – REVISED NOVEMBER 1997

J (R-GDIP-T**)

CERAMIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN

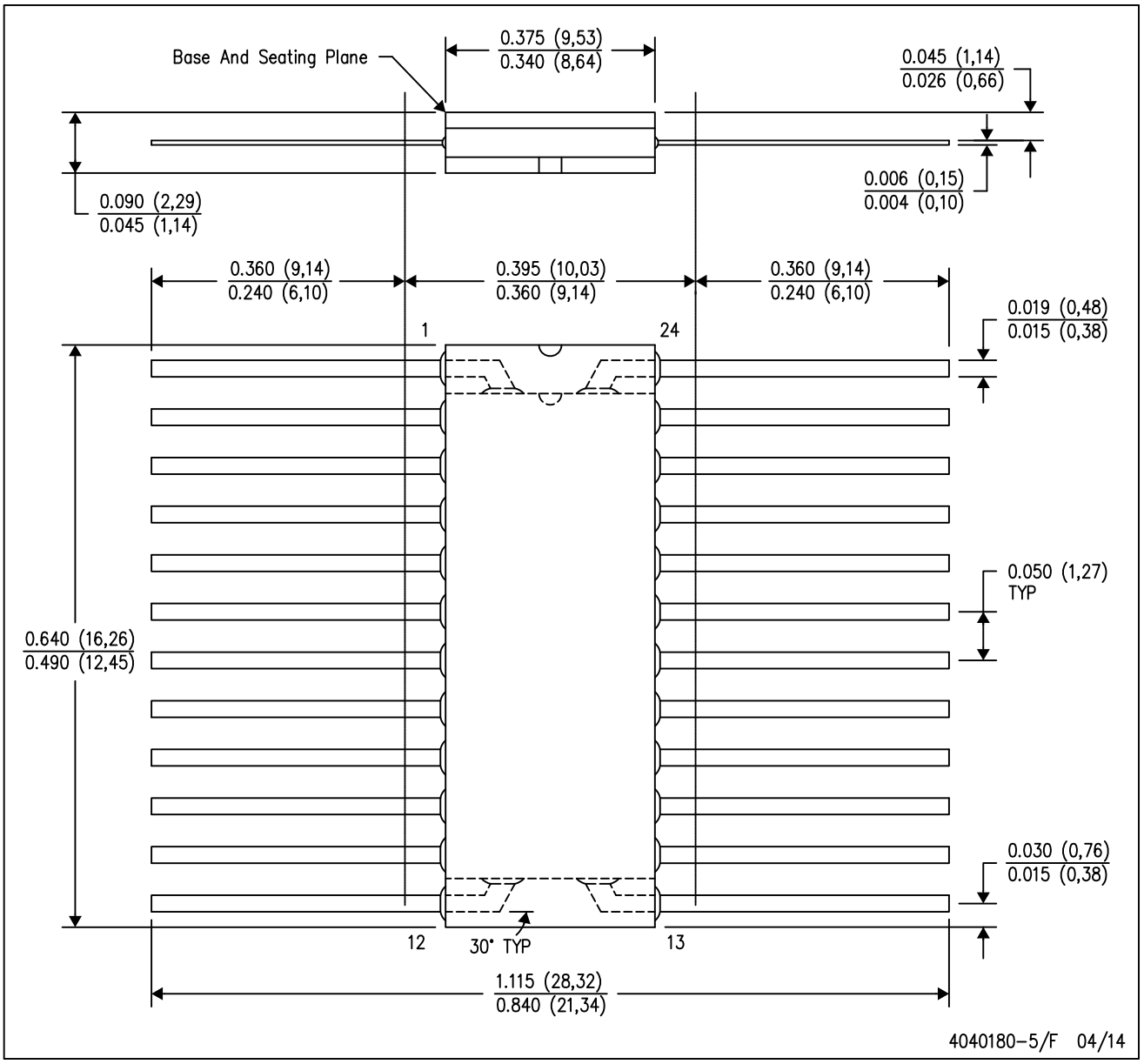


DIM \ PINS **		24		28		32		40	
		NARR	WIDE	NARR	WIDE	NARR	WIDE	NARR	WIDE
"A"	MAX	0.624(15,85)	0.624(15,85)	0.624(15,85)	0.624(15,85)	0.624(15,85)	0.624(15,85)	0.624(15,85)	0.624(15,85)
	MIN	0.590(14,99)	0.590(14,99)	0.590(14,99)	0.590(14,99)	0.590(14,99)	0.590(14,99)	0.590(14,99)	0.590(14,99)
"B"	MAX	1.265(32,13)	1.265(32,13)	1.465(37,21)	1.465(37,21)	1.668(42,37)	1.668(42,37)	2.068(52,53)	2.068(52,53)
	MIN	1.235(31,37)	1.235(31,37)	1.435(36,45)	1.435(36,45)	1.632(41,45)	1.632(41,45)	2.032(51,61)	2.032(51,61)
"C"	MAX	0.541(13,74)	0.598(15,19)	0.541(13,74)	0.598(15,19)	0.541(13,74)	0.598(15,19)	0.541(13,74)	0.598(15,19)
	MIN	0.514(13,06)	0.571(14,50)	0.514(13,06)	0.571(14,50)	0.514(13,06)	0.571(14,50)	0.514(13,06)	0.571(14,50)

4040084/C 10/97

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Window (lens) added to this group of packages (24-, 28-, 32-, 40-pin).
D. This package can be hermetically sealed with a ceramic lid using glass frit.
E. Index point is provided on cap for terminal identification.

W (R–GDFP–F24) CERAMIC DUAL FLATPACK



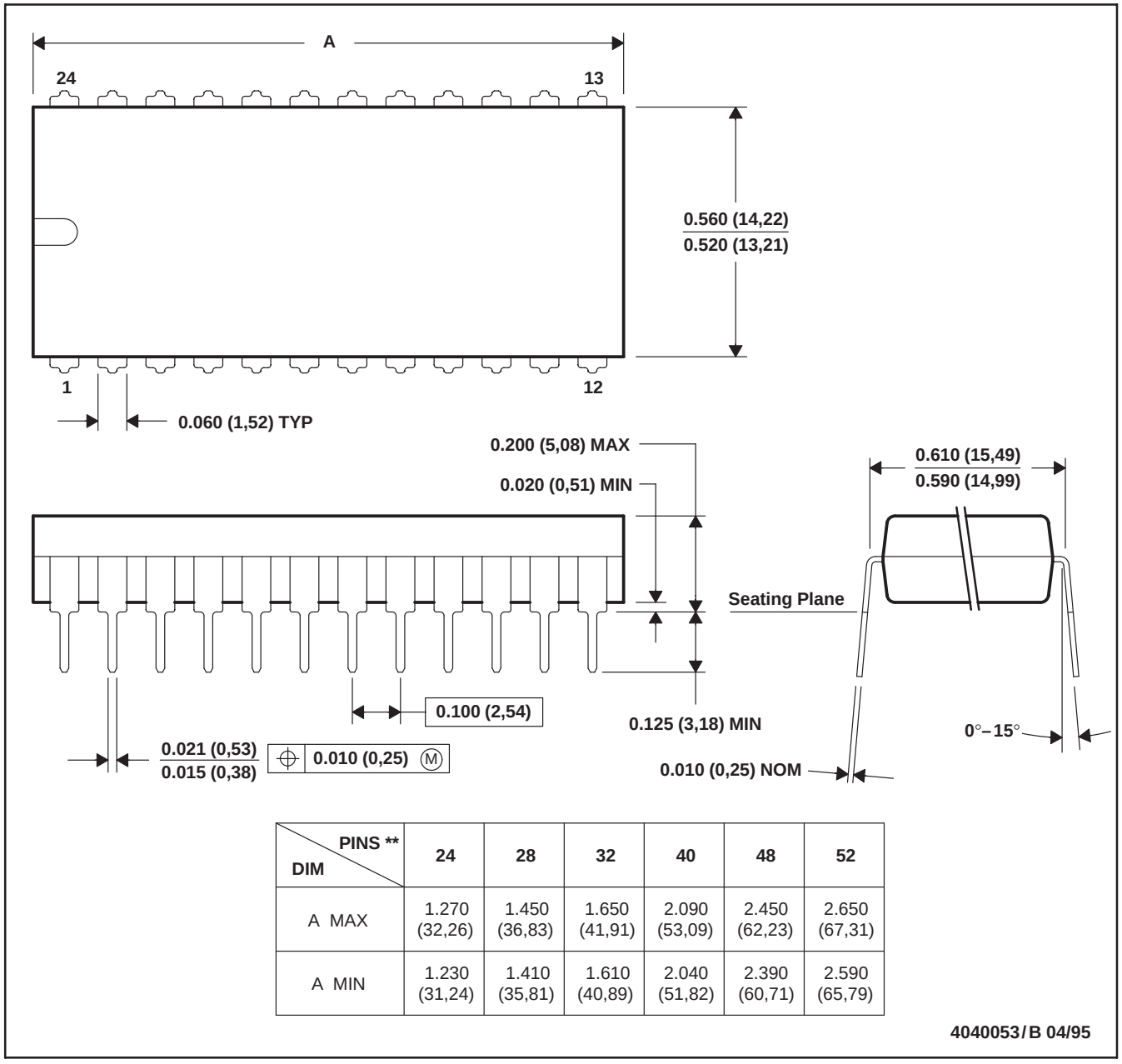
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within Mil–Std 1835 GDFP2–F20

MPDI008 – OCTOBER 1994

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PIN SHOWN



DIM \ PINS **	24	28	32	40	48	52
A MAX	1.270 (32,26)	1.450 (36,83)	1.650 (41,91)	2.090 (53,09)	2.450 (62,23)	2.650 (67,31)
A MIN	1.230 (31,24)	1.410 (35,81)	1.610 (40,89)	2.040 (51,82)	2.390 (60,71)	2.590 (65,79)

4040053/B 04/95

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-011
D. Falls within JEDEC MS-015 (32 pin only)

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